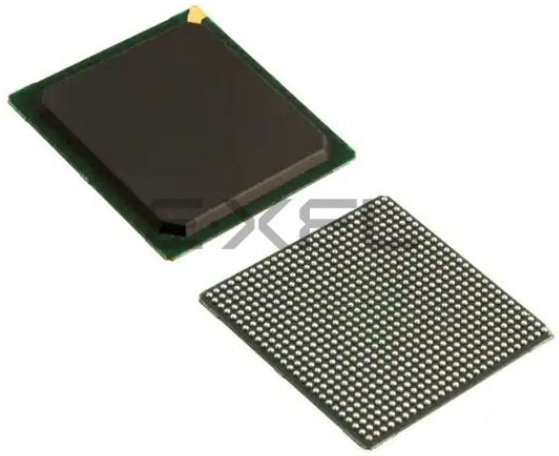


Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	18144
Number of Logic Elements/Cells	-
Total RAM Bits	165888
Number of I/O	418
Number of Gates	1000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax1000-2fgg676i

The SRAM blocks are arranged in a column on the west side of the tile (Figure 1-6 on page 1-4).

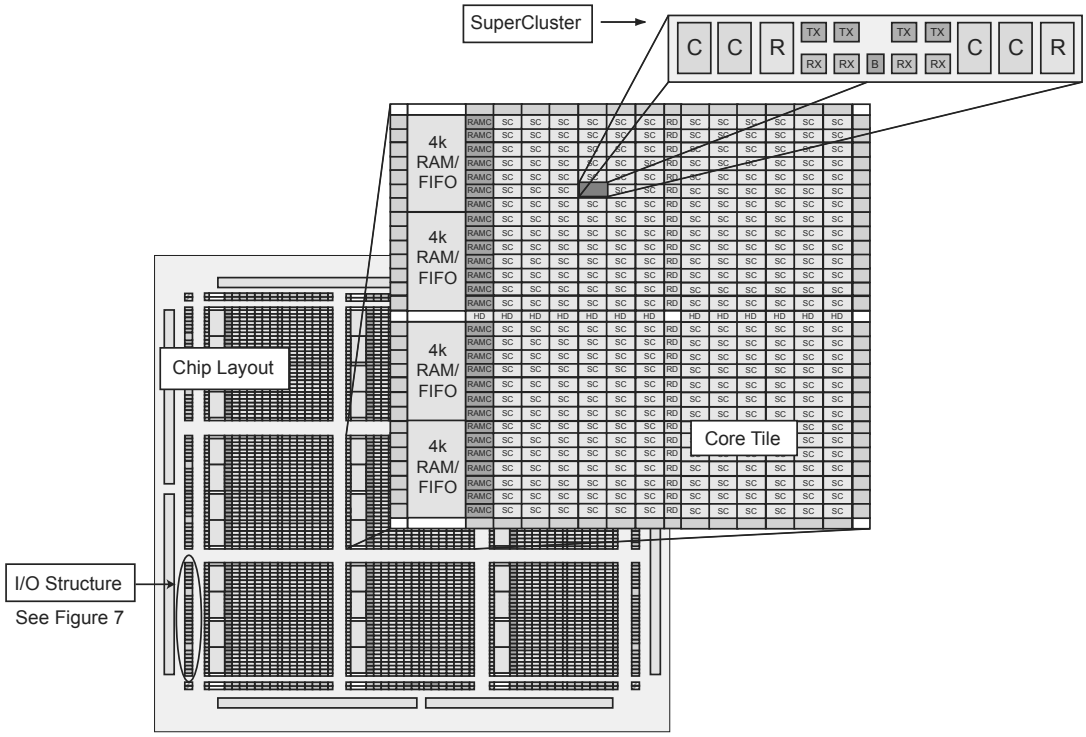


Figure 1-6 • **AX Device Architecture (AX1000 shown)**

Embedded Memory

As mentioned earlier, each core tile has either three (in a smaller tile) or four (in the regular tile) embedded SRAM blocks along the west side, and each variable-aspect-ratio SRAM block is 4,608 bits in size. Available memory configurations are: 128x36, 256x18, 512x9, 1kx4, 2kx2 or 4kx1 bits. The individual blocks have separate read and write ports that can be configured with different bit widths on each port. For example, data can be written in by eight and read out by one.

In addition, every SRAM block has an embedded FIFO control unit. The control unit allows the SRAM block to be configured as a synchronous FIFO without using core logic modules. The FIFO width and depth are programmable. The FIFO also features programmable ALMOST-EMPTY (AEMPTY) and ALMOST-FULL (AFULL) flags in addition to the normal EMPTY and FULL flags. In addition to the flag logic, the embedded FIFO control unit also contains the counters necessary for the generation of the read and write address pointers as well as control circuitry to prevent metastability and erroneous operation. The embedded SRAM/FIFO blocks can be cascaded to create larger configurations.

I/O Logic

The Axcelerator family of FPGAs features a flexible I/O structure, supporting a range of mixed voltages with its bank-selectable I/Os: 1.5V, 1.8V, 2.5V, and 3.3V. In all, Axcelerator FPGAs support at least 14 different I/O standards (single-ended, differential, voltage-referenced). The I/Os are organized into banks, with eight banks per device (two per side). The configuration of these banks determines the I/O standards supported (see "User I/Os" on page 2-11 for more information). All I/O standards are available in each bank.

Each I/O module has an input register (InReg), an output register (OutReg), and an enable register (EnReg) (Figure 1-7 on page 1-5). An I/O Cluster includes two I/O modules, four RX modules, two TX modules, and a buffer (B) module.

Thermal Characteristics

Introduction

The temperature variable in Microsemi's Designer software refers to the junction temperature, not the ambient temperature. This is an important distinction because dynamic and static power consumption cause the chip junction temperature to be higher than the ambient temperature. EQ 1 can be used to calculate junction temperature.

T_J = Junction Temperature = $\Delta T + T_a$

EQ 1

Where:

T_a = Ambient Temperature

ΔT = Temperature gradient between junction (silicon) and ambient

$\Delta T = \theta_{ja} * P$

EQ 2

Where:

P = Power

θ_{ja} = Junction to ambient of package. θ_{ja} numbers are located under Table 2-6 on page 2-7.

Package Thermal Characteristics

The device junction-to-case thermal characteristic is θ_{jc}, and the junction-to-ambient air characteristic is θ_{ja}. The thermal characteristics for θ_{ja} are shown with two different air flow rates. θ_{jc} values are provided for reference. The absolute maximum junction temperature is 125°C.

The maximum power dissipation allowed for commercial- and industrial-grade devices is a function of θ_{ja}. A sample calculation of the absolute maximum power dissipation allowed for an 896-pin FBGA package at commercial temperature and still air is as follows:

$$\text{Maximum Power Allowed} = \frac{\text{Max. junction temp. } (°C) - \text{Max. ambient temp. } (°C)}{\theta_{ja}(°C/W)} = \frac{125°C - 70°C}{13.6°C/W} = 4.04\ W$$

User-Defined Supply Pins

VREF **Supply Voltage**

Reference voltage for I/O banks. VREF pins are configured by the user from regular I/O pins; VREF pins are not in fixed locations. There can be one or more VREF pins in an I/O bank.

Global Pins

HCLKA/B/C/D **Dedicated (Hardwired) Clocks A, B, C and D**

These pins are the clock inputs for sequential modules or north PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. This input is directly wired to each R-cell and offers clock speeds independent of the number of R-cells being driven. When the HCLK pins are unused, it is recommended that they are tied to ground.

CLKE/F/G/H **Routed Clocks E, F, G, and H**

These pins are clock inputs for clock distribution networks or south PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. The clock input is buffered prior to clocking the R-cells. When the CLK pins are unused, Microsemi recommends that they are tied to ground.

JTAG/Probe Pins

PRA/B/C/D **Probe A, B, C and D**

The Probe pins are used to output data from any user-defined design node within the device (controlled with Silicon Explorer II). These independent diagnostic pins can be used to allow real-time diagnostic output of any signal path within the device. The pins' probe capabilities can be permanently disabled to protect programmed design confidentiality. The probe pins are of LVTTL output levels.

TCK **Test Clock**

Test clock input for JTAG boundary-scan testing and diagnostic probe (Silicon Explorer II).

TDI **Test Data Input**

Serial input for JTAG boundary-scan testing and diagnostic probe. TDI is equipped with an internal 10 kΩ pull-up resistor.

TDO **Test Data Output**

Serial output for JTAG boundary-scan testing.

TMS **Test Mode Select**

The TMS pin controls the use of the IEEE 1149.1 boundary-scan pins (TCK, TDI, TDO, TRST). TMS is equipped with an internal 10 kΩ pull-up resistor.

TRST **Boundary Scan Reset Pin**

The TRST pin functions as an active-low input to asynchronously initialize or reset the boundary scan circuit. The TRST pin is equipped with a 10 kΩ pull-up resistor.

Special Functions

LP **Low Power Pin**

The LP pin controls the low power mode of Axcelerator devices. The device is placed in the low power mode by connecting the LP pin to logic high. To exit the low power mode, the LP pin must be set Low. Additionally, the LP pin must be set Low during chip powering-up or chip powering-down operations. See "Low Power Mode" on page 2-106 for more details.

NC **No Connection**

This pin is not connected to circuitry within the device. These pins can be driven to any voltage or can be left floating with no effect on the operation of the device.

Using the Differential I/O Standards

Differential I/O macros should be instantiated in the netlist. The settings for these I/O standards cannot be changed inside Designer. Note that there are no tristated or bidirectional I/O buffers for differential standards.

Using the Voltage-Referenced I/O Standards

Using these I/O standards is similar to that of single-ended I/O standards. Their settings can be changed in Designer.

Using DDR (Double Data Rate)

In Double Data Rate mode, new data is present on every transition of the clock signal. Clock and data lines have identical bandwidth and signal integrity requirements, making it very efficient for implementing very high-speed systems.

To implement a DDR, users need to:

1. Instantiate an input buffer (with the required I/O standard)
2. Instantiate the DDR_REG macro (Figure 2-6)
3. Connect the output from the Input buffer to the input of the DDR macro

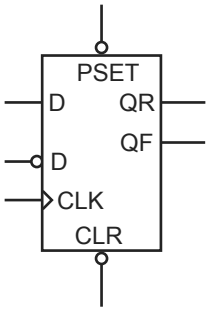


Figure 2-6 • **DDR Register**

Macros for Specific I/O Standards

There are different macro types for any I/O standard or feature that determine the required VCCI and VREF voltages for an I/O. The generic buffer macros require the LVTTL standard with slow slew rate and 24 mA-drive strength. LVTTL can support high slew rate but this should only be used for critical signals.

Most of the macro symbols represent variations of the six generic symbol types:

- CLKBUF: Clock Buffer
- HCLKBUF: Hardwired Clock Buffer
- INBUF: Input Buffer
- OUTBUF: Output Buffer
- TRIBUF: Tristate Buffer
- BIBUF: Bidirectional Buffer

Other macros include the following:

- Differential I/O standard macros: The LVDS and LVPECL macros either have a pair of differential inputs (e.g. INBUF_LVDS) or a pair of differential outputs (e.g. OUTBUF_LVPECL).
- Pull-up and pull-down variations of the INBUF, BIBUF, and TRIBUF macros. These are available only with TTL and LVCMOS thresholds. They can be used to model the behavior of the pull-up and pull-down resistors available in the architecture. Whenever an input pin is left unconnected, the output pin will either go high or low rather than unknown. This allows users to leave inputs unconnected without having the negative effect on simulation of propagating unknowns.
- DDR_REG macro. It can be connected to any I/O standard input buffers (i.e. INBUF) to implement a double data rate register. Designer software will map it to the I/O module in the same way it maps the other registers to the I/O module.

Carry-Chain Logic

The Axcelerator dedicated carry-chain logic offers a very compact solution for implementing arithmetic functions without sacrificing performance.

To implement the carry-chain logic, two C-cells in a Cluster are connected together so the FCO (i.e. carry out) for the two bits is generated in a carry look-ahead scheme to achieve minimum propagation delay from the FCI (i.e. carry in) into the two-bit Cluster. The two-bit carry logic is shown in Figure 2-29.

The FCI of one C-cell pair is driven by the FCO of the C-cell pair immediately above it. Similarly, the FCO of one C-cell pair, drives the FCI input of the C-cell pair immediately below it (Figure 1-4 on page 1-3 and Figure 2-30 on page 2-57).

The carry-chain logic is selected via the CFN input. When carry logic is not required, this signal is deasserted to save power. Again, this configuration is handled automatically for the user through Microsemi's macro library.

The signal propagation delay between two C-cells in the carry-chain sequence is 0.1 ns.

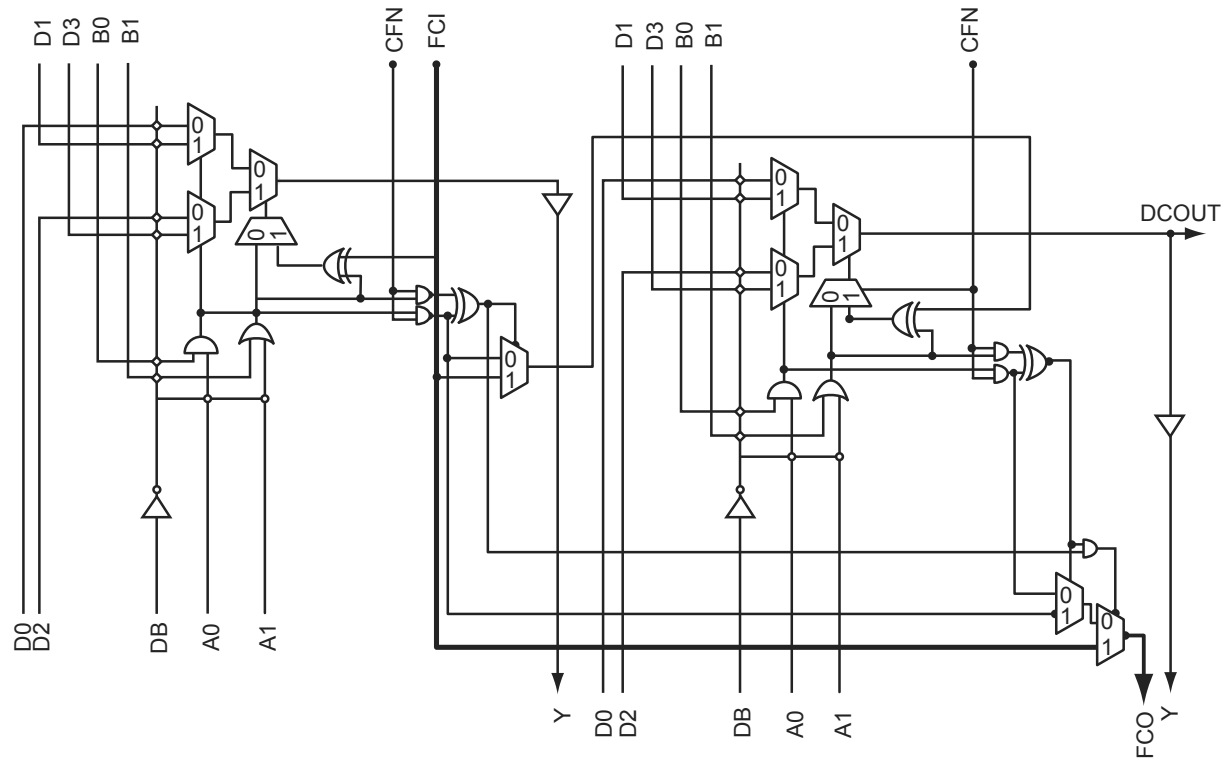
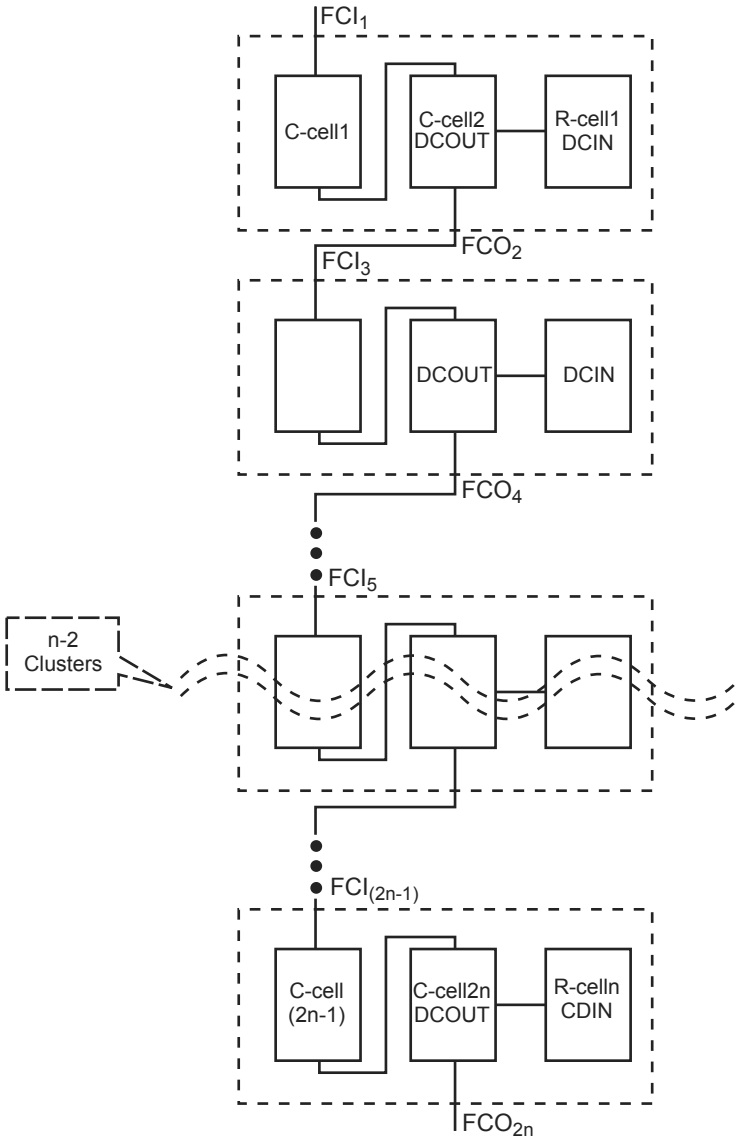


Figure 2-29 • **Axcelerator's Two-Bit Carry Logic**



Note: The carry-chain sequence can end on either C-cell.

Figure 2-30 • **Carry-Chain Sequencing of C-Cells**

Timing Characteristics

Refer to Table 2-62 on page 2-55 for more information on carry-chain timing.

PLLRCLK and PLLHCLK

PLLRCLK (PLLHCLK) is used to drive global resource CLK (HCLK) from a PLL (Figure 2-44).

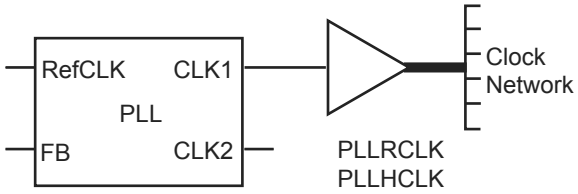


Figure 2-44 • **PLLRCLK and PLLHCLK**

Using Global Resources with PLLs

Each global resource has an associated PLL at its root. For example, PLLA can drive HCLKA, PLLE can drive CLKE, etc. (Figure 2-45).

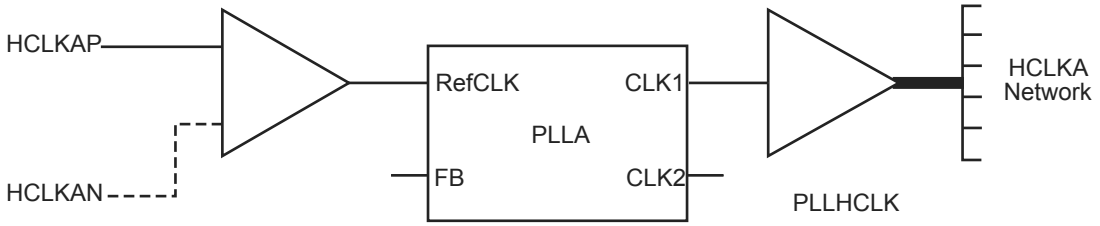


Figure 2-45 • **Example of HCLKA Driven from a PLL with External Clock Source**

In addition, each clock pin of the package can be used to drive either its associated global resource or PLL. For example, package pins CLKEP and CLKEN can drive either the RefCLK input of PLLE or CLKE.

There are two macros required when interfacing the embedded PLLs with the global resources: PLLINT and PLLOUT.

PLLINT

This macro is used to drive the RefCLK input of the PLL internally from user signals.

PLLOUT

This macro is used to connect either the CLK1 or CLK2 output of a PLL to the regular routing network (Figure 2-46).

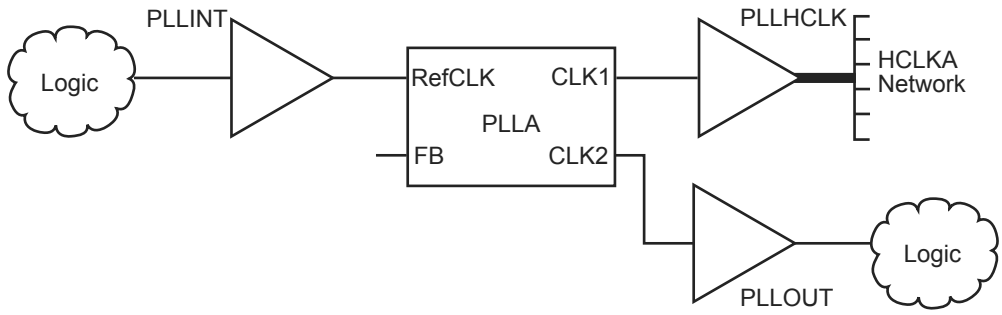


Figure 2-46 • **Example of PLLINT and PLLOUT Usage**

***Table 2-80* • PLL Interface Signals**

Signal Name	Type	User Accessible	Allowable Values	Function
RefCLK	Input	Yes		Reference Clock for the PLL
FB	Input	Yes		Feedback port for the PLL
PowerDown	Input	Yes		PLL power down control
			0	PLL powered down
			1	PLL active
DIVI[5:0]	Input	Yes	1 to 64, in unsigned binary notation offset by -1	Sets value for feedback divider (multiplier)
DIVJ[5:0]	Input	Yes		Sets value for CLK1 divider
LowFreq	Input	Yes		Input frequency range selector
			0	50–200 MHz
			1	14–50 MHz
Osc[2:0]	Input	Yes		Output frequency range selector
			XX0	400–1000 MHZ
			001	200–400 MHZ
			011	100–200 MHZ
			101	50–100 MHZ
			111	20–50 MHZ
DelayLine[4:0]	Input	Yes	–15 to +15 (increments), in signed-and-magnitude binary representation	Clock Delay (positive/negative) in increments of 250 ps, with maximum value of ± 3.75 ns
FBMuxSel	Input	No		Selects the source for the feedback input
REFSEL	Input	No		Selects the source for the reference clock
OUTSEL	Input	No		Selects the source for the routed net output
PLLSEL	Input	No		ROOTSEL & PLLSEL are used to select the source of the global clock network
ROOTSEL	Input	No		
Lock	Output	Yes		High value indicates PLL has locked
CLK1	Output	Yes		PLL clock output
CLK2	Output	Yes		PLL clock output

Note: If the input RefClk is taken outside its operating range, the outputs Lock, CLK1 and CLK2 are indeterminate.

***Table 2-89* • One RAM Block**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		1.08		1.23		1.45	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.22		0.25		0.30	ns
t_{WADSU}	Write Address Setup vs. WCLK		1.08		1.23		1.45	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		1.08		1.23		1.45	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.22		0.25		0.30	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	0.88		0.88		0.88		ns
t_{WCKP}	WCLK Minimum Period	1.63		1.63		1.63		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		0.81		0.92		1.08	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		0.81		0.92		1.08	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-to-OUT (Pipelined)		1.32		1.51		1.77	ns
$t_{RCK2RD2}$	RCLK-to-OUT (Non-Pipelined)		2.16		2.46		2.90	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.77		0.77		0.77		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	0.93		0.93		0.93		ns
t_{RCKP}	RCLK Minimum Period	1.70		1.70		1.70		ns

Note: Timing data for this single block RAM has a depth of 4,096. For all other combinations, use Microsemi's timing software.

FIFO

Every memory block has its own embedded FIFO controller. Each FIFO block has one read port and one write port. This embedded FIFO controller uses no internal FPGA logic and features:

- Glitch-free FIFO Flags
- Gray-code address counters/pointers to prevent metastability problems
- Overflow and underflow control

Both ports are configurable in various sizes from 4k x 1 to 128 x 36, similar to the RAM block size. Each port is fully synchronous.

Read and write operations can be completely independent. Data on the appropriate WD pins are written to the FIFO on every active WCLK edge as long as WEN is high. Data is read from the FIFO and output on the appropriate RD pins on every active RCLK edge as long as REN is asserted.

The FIFO block offers programmable almost-empty (AEMPTY) and almost-full (AFULL) flags as well as EMPTY and FULL flags (Figure 2-61):

- The FULL flag is synchronous to WCLK. It allows the FIFO to inhibit writing when full.
- The EMPTY flag is synchronous to RCLK. It allows the FIFO to inhibit reading at the empty condition.

Gray code counters are used to prevent metastability problems associated with flag logic. The depth of the FIFO is dependent on the data width and the number of memory blocks used to create the FIFO. The write operations to the FIFO are synchronous with respect to the WCLK, and the read operations are synchronous with respect to the RCLK.

The FIFO block may be reset to the empty state.

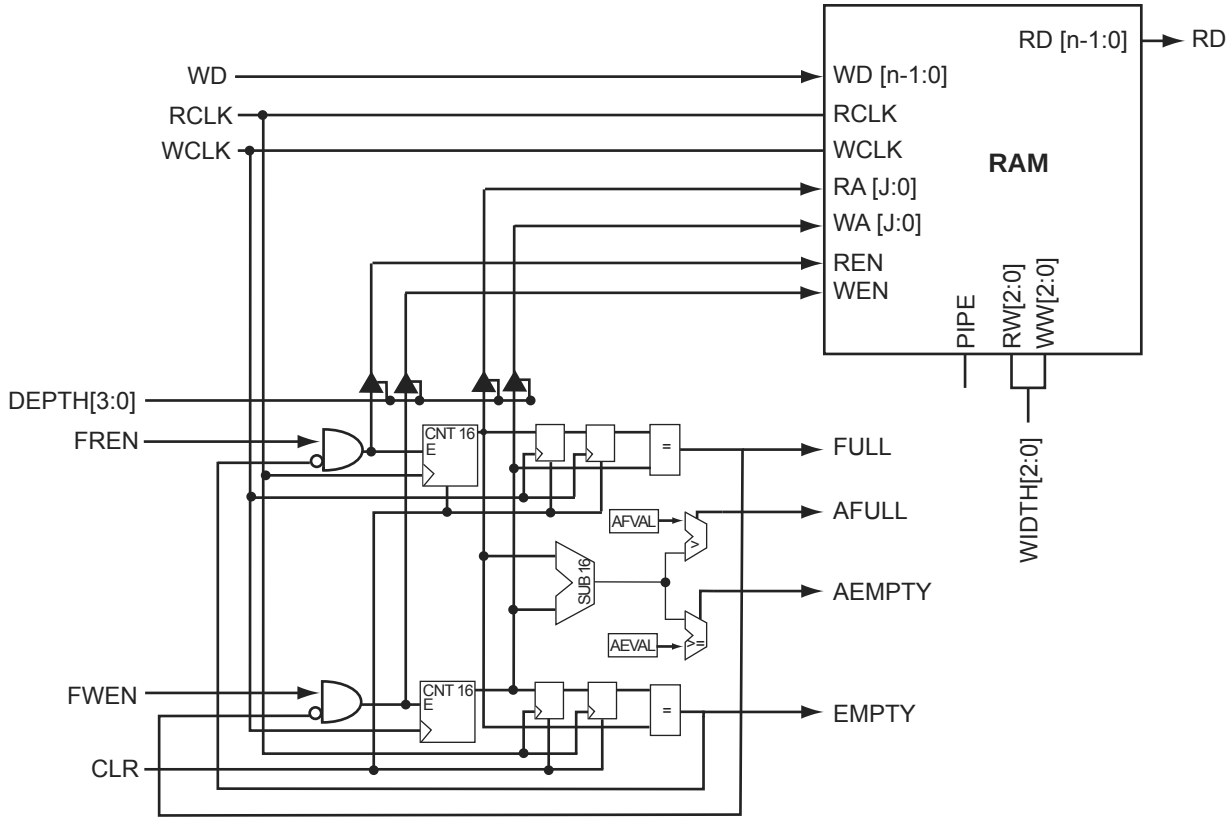


Figure 2-61 • **Axcelerator RAM with Embedded FIFO Controller**

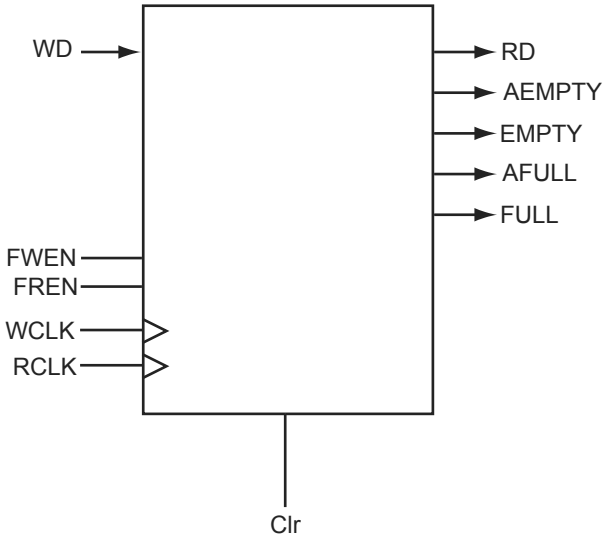


Figure 2-66 • **FIFO Model**

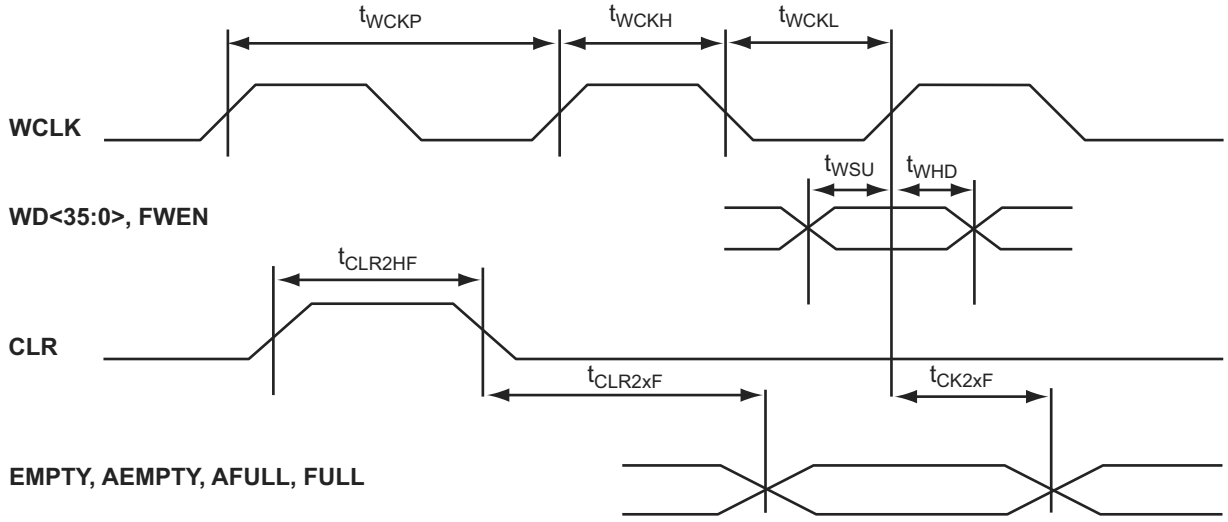


Figure 2-67 • **FIFO Write Timing**

Programming

Device programming is supported through the Silicon Sculptor II, a single-site, robust and compact device programmer for the PC. Up to four Silicon Sculptor IIs can be daisy-chained and controlled from a single PC host. With standalone software for the PC, Silicon Sculptor II is designed to allow concurrent programming of multiple units from the same PC when daisy-chained.

Silicon Sculptor II programs devices independently to achieve the fastest programming times possible. Each fuse is verified by Silicon Sculptor II to ensure correct programming. Furthermore, at the end of programming, there are integrity tests that are run to ensure that programming was completed properly. Not only does it test programmed and nonprogrammed fuses, Silicon Sculptor II also provides a self-test to test its own hardware extensively.

Programming an Axcelerator device using Silicon Sculptor II is similar to programming any other antifuse device. The procedure is as follows:

1. Load the *.AFM file.
2. Select the device to be programmed.
3. Begin programming.

When the design is ready to go to production, Microsemi offers device volume-programming services either through distribution partners or via our In-House Programming Center.

In addition, BP Microsystems offers multi-site programmers that provide qualified support for Axcelerator devices.

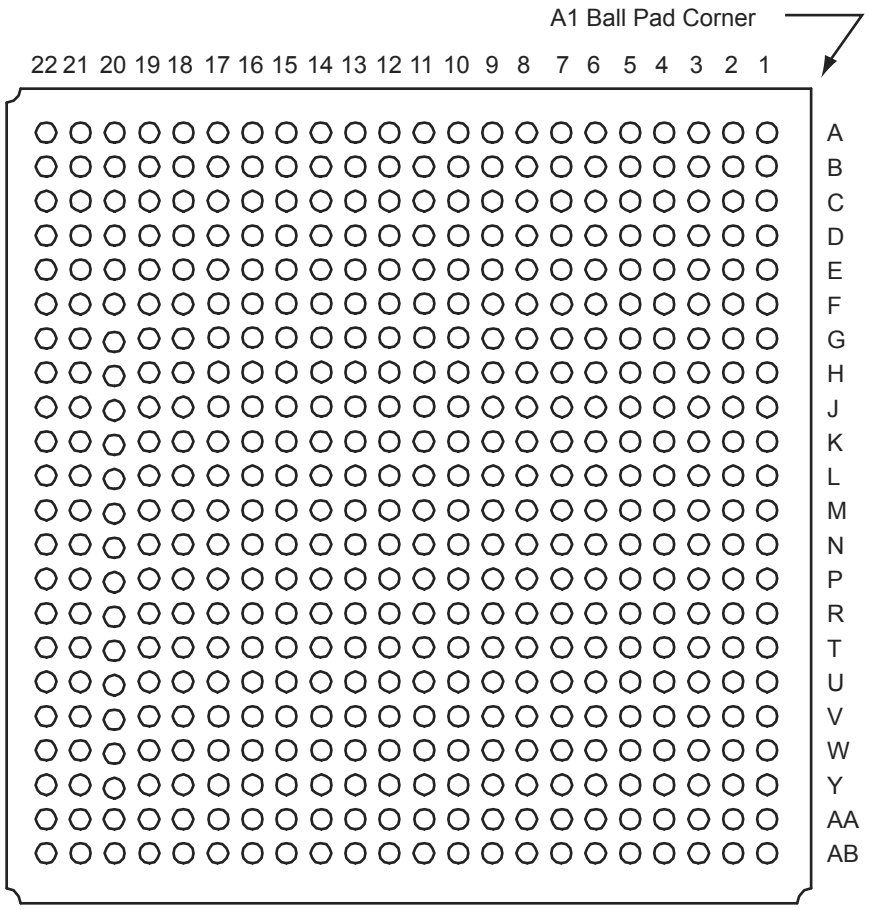
For more details on programming the Axcelerator devices, please refer to the *Silicon Sculptor II User's Guide*.

FG324	
AX125 Function	**Pin Number**
IO50NB4F4/CLKFN	U9
IO50PB4F4/CLKFP	U10
Bank 5	
IO51NB5F5/CLKGN	R8
IO51PB5F5/CLKGP	R9
IO52NB5F5/CLKHN	T7
IO52PB5F5/CLKHP	T8
IO53NB5F5	U6
IO53PB5F5	U7
IO54NB5F5	V8
IO54PB5F5	V9
IO55NB5F5	V6
IO55PB5F5	V7
IO56NB5F5	U4
IO56PB5F5	U5
IO57NB5F5	T4
IO57PB5F5	T5
IO58NB5F5	V4
IO58PB5F5	V5
IO59NB5F5	V2
IO59PB5F5	V3
Bank 6	
IO60NB6F6	P5
IO60PB6F6	P6
IO61NB6F6	T2
IO61PB6F6	U3
IO62NB6F6	T1
IO62PB6F6	U1
IO63NB6F6	P1
IO63PB6F6	R1
IO64NB6F6	R3
IO64PB6F6	P3
IO65NB6F6	P2
IO65PB6F6	R2
IO66NB6F6	M3

FG324	
AX125 Function	**Pin Number**
IO66PB6F6	N3
IO67NB6F6	M2
IO67PB6F6	N2
IO68NB6F6	M1
IO68PB6F6	N1
IO69NB6F6	K4
IO69PB6F6	L4
IO70NB6F6	K1
IO70PB6F6	L1
IO71NB6F6	K3
IO71PB6F6	L3
Bank 7	
IO72NB7F7	H4
IO72PB7F7	J4
IO73NB7F7	K2
IO73PB7F7	L2
IO74NB7F7	H2
IO74PB7F7	H1
IO75NB7F7	H3
IO75PB7F7	J3
IO76NB7F7	F2
IO76PB7F7	G2
IO77NB7F7	F1
IO77PB7F7	G1
IO78NB7F7	D2
IO78PB7F7	E2
IO79NB7F7	F3
IO79PB7F7	G3
IO80NB7F7	E3
IO80PB7F7	E4
IO81NB7F7	D1
IO81PB7F7	E1
IO82NB7F7	D3
IO82PB7F7	C2
IO83NB7F7	B1

FG324	
AX125 Function	**Pin Number**
IO83PB7F7	C1
Dedicated I/O	
VCCDA	F5
GND	A1
GND	A18
GND	B17
GND	B2
GND	C16
GND	C3
GND	E16
GND	F13
GND	F6
GND	G12
GND	G7
GND	H10
GND	H11
GND	H8
GND	H9
GND	J10
GND	J11
GND	J8
GND	J9
GND	K10
GND	K11
GND	K8
GND	K9
GND	L10
GND	L11
GND	L8
GND	L9
GND	M12
GND	M7
GND	N13
GND	N6
GND	R14

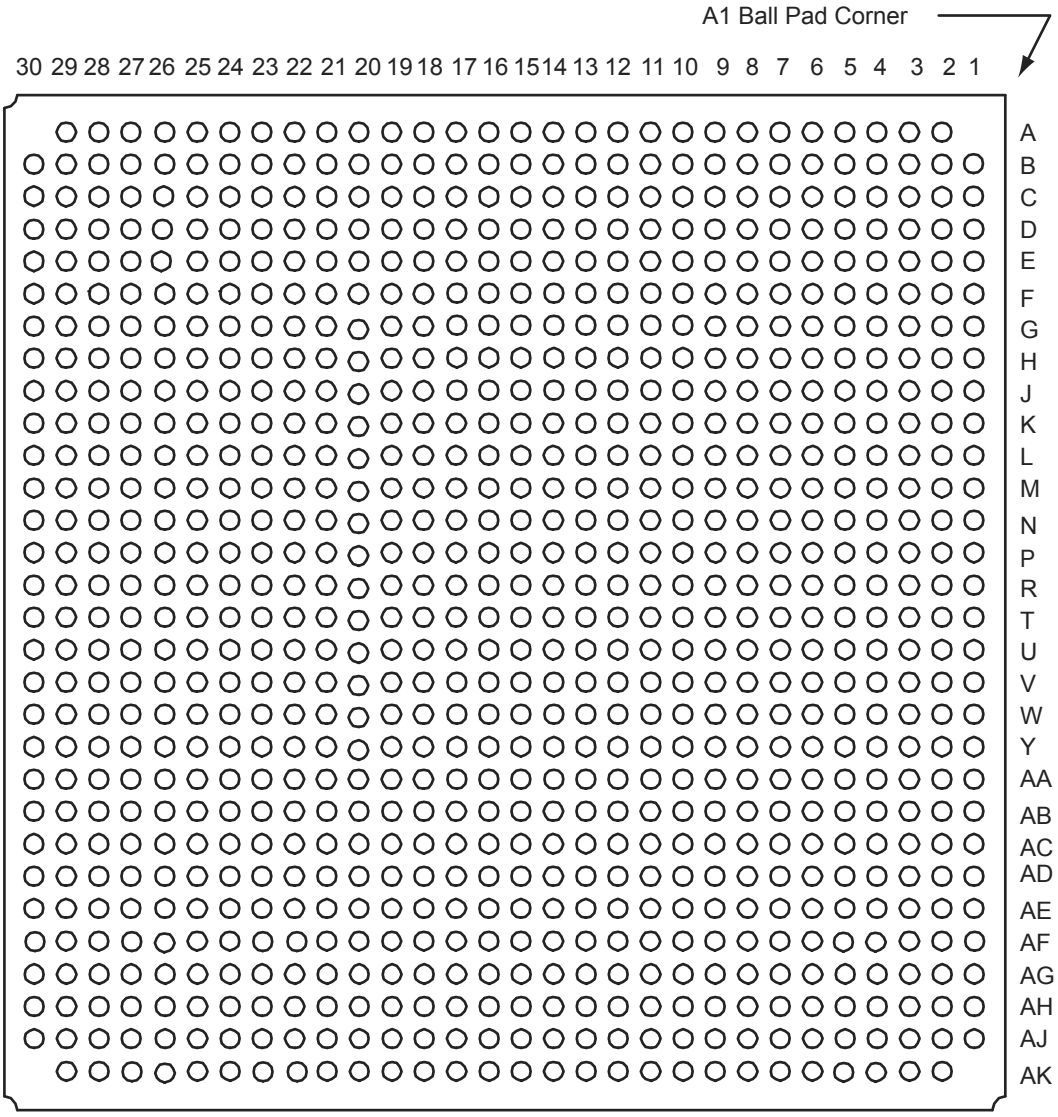
FG484



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG896



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG896	
AX1000 Function	Pin Number
NC	K1
NC	K2
NC	L30
NC	M30
NC	N29
NC	T1
NC	U1
NC	W30
NC	Y1
NC	Y2
NC	Y30
PRA	G15
PRB	D16
PRC	AB16
PRD	AF16
TCK	G7
TDI	D5
TDO	J8
TMS	F6
TRST	C4
VCCA	AD6
VCCA	AH26
VCCA	E28
VCCA	E3
VCCA	L12
VCCA	L13
VCCA	L14
VCCA	L15
VCCA	L16
VCCA	L17
VCCA	L18
VCCA	L19
VCCA	M11
VCCA	M20
VCCA	N11

FG896	
AX1000 Function	Pin Number
VCCA	N20
VCCA	P11
VCCA	P20
VCCA	R11
VCCA	R20
VCCA	T11
VCCA	T20
VCCA	U11
VCCA	U20
VCCA	V11
VCCA	V20
VCCA	W11
VCCA	W20
VCCA	Y12
VCCA	Y13
VCCA	Y14
VCCA	Y15
VCCA	Y16
VCCA	Y17
VCCA	Y18
VCCA	Y19
VCCPLA	G14
VCCPLB	H15
VCCPLC	G17
VCCPLD	J16
VCCPLE	AH17
VCCPLF	AC16
VCCPLG	AH14
VCCPLH	AD15
VCCDA	AD24
VCCDA	AD7
VCCDA	AF12
VCCDA	AF13
VCCDA	AF15
VCCDA	AF18

FG896	
AX1000 Function	Pin Number
VCCDA	AF19
VCCDA	C13
VCCDA	C5
VCCDA	D13
VCCDA	D19
VCCDA	D3
VCCDA	E18
VCCDA	F26
VCCDA	G16
VCCDA	T25
VCCDA	T4
VCCIB0	A3
VCCIB0	B3
VCCIB0	J10
VCCIB0	J11
VCCIB0	J12
VCCIB0	K11
VCCIB0	K12
VCCIB0	K13
VCCIB0	K14
VCCIB0	K15
VCCIB1	A28
VCCIB1	B28
VCCIB1	J19
VCCIB1	J20
VCCIB1	J21
VCCIB1	K16
VCCIB1	K17
VCCIB1	K18
VCCIB1	K19
VCCIB1	K20
VCCIB2	C29
VCCIB2	C30
VCCIB2	K22
VCCIB2	L21

FG896	
AX2000 Function	Pin Number
IO65PB1F6	H20
IO66NB1F6	B23
IO66PB1F6	B21
IO67NB1F6	H21
IO67PB1F6	G21
IO68NB1F6	D22
IO68PB1F6	C22
IO69NB1F6	A25
IO69PB1F6	A24
IO70NB1F6	F22
IO70PB1F6	E22
IO71NB1F6	F21
IO71PB1F6	E21
IO73NB1F6	C24
IO73PB1F6	C23
IO74NB1F6	D24
IO74PB1F6	D23
IO75NB1F6	H23
IO75PB1F6	H22
IO76NB1F7	B25
IO76PB1F7	B24
IO78NB1F7	B26
IO78PB1F7	A26
IO79NB1F7	F23
IO79PB1F7	E23
IO80NB1F7	D25
IO80PB1F7	C25
IO81NB1F7	G23
IO81PB1F7	G22
IO82NB1F7	B27
IO82PB1F7	A27
IO83NB1F7	F24
IO83PB1F7	E24
IO84NB1F7	D26
IO84PB1F7	C26

FG896	
AX2000 Function	Pin Number
IO85NB1F7	F25
IO85PB1F7	E25
Bank 2	
IO86NB2F8	G26
IO86PB2F8	G25
IO87NB2F8	K23
IO87PB2F8	J23
IO88NB2F8	J24
IO88PB2F8	H24
IO89NB2F8	E29
IO89PB2F8	D29
IO90NB2F8	F27
IO90PB2F8	E27
IO91NB2F8	H26
IO91PB2F8	H25
IO92NB2F8	G28
IO92PB2F8	F28
IO93NB2F8	J26
IO93PB2F8	J25
IO94NB2F8	H27
IO94PB2F8	G27
IO95NB2F8	H29
IO95PB2F8	G29
IO96NB2F9	G30
IO96PB2F9	F30
IO97NB2F9	K25
IO97PB2F9	K24
IO98NB2F9	J28
IO98PB2F9	H28
IO99NB2F9	L23
IO99PB2F9	L24
IO100NB2F9	K27
IO100PB2F9	J27
IO101PB2F9	J30
IO102NB2F9	E30

FG896	
AX2000 Function	Pin Number
IO102PB2F9	D30
IO103NB2F9	L26
IO103PB2F9	K26
IO104NB2F9	F29
IO105NB2F9	M25
IO105PB2F9	L25
IO106NB2F9	K30
IO106PB2F9	K29
IO107NB2F10	M23
IO107PB2F10	M24
IO109NB2F10	M27
IO109PB2F10	L27
IO110NB2F10	M28
IO110PB2F10	L28
IO111NB2F10	N22
IO111PB2F10	N23
IO112NB2F10	M29
IO112PB2F10	L29
IO113NB2F10	N26
IO113PB2F10	M26
IO114NB2F10	M30
IO114PB2F10	L30
IO115NB2F10	N28
IO115PB2F10	N27
IO117NB2F10	N25
IO117PB2F10	N24
IO118NB2F11	N29
IO119NB2F11	P22
IO119PB2F11	P23
IO121NB2F11	P25
IO121PB2F11	P24
IO122NB2F11	P28
IO122PB2F11	P27
IO123NB2F11	R26
IO123PB2F11	P26

FG896	
AX2000 Function	Pin Number
IO245PB5F23	AG8
IO246NB5F23	AD8
IO246PB5F23	AD9
IO247NB5F23	AG7
IO247PB5F23	AH7
IO248NB5F23	AK5
IO249NB5F23	AJ5
IO249PB5F23	AJ6
IO250NB5F23	AC8
IO250PB5F23	AC9
IO251NB5F23	AH6
IO251PB5F23	AG6
IO252NB5F23	AF6
IO252PB5F23	AF7
IO253NB5F23	AG2
IO253PB5F23	AG1
IO254NB5F23	AE7
IO254PB5F23	AE8
IO255NB5F23	AG5
IO255PB5F23	AH5
IO256NB5F23	AJ4
IO256PB5F23	AK4
Bank 6	
IO257NB6F24	AE4
IO257PB6F24	AF4
IO258NB6F24	AB7
IO258PB6F24	AC7
IO259NB6F24	AD5
IO259PB6F24	AE5
IO260NB6F24	AF1
IO260PB6F24	AF2
IO261NB6F24	AF3
IO261PB6F24	AG3
IO262NB6F24	AC4
IO262PB6F24	AD4

FG896	
AX2000 Function	Pin Number
IO263NB6F24	AD3
IO263PB6F24	AE3
IO264NB6F24	AB6
IO264PB6F24	AC6
IO265NB6F24	AD1
IO265PB6F24	AE1
IO266NB6F24	AA8
IO266PB6F24	AB8
IO267NB6F25	AB5
IO267PB6F25	AC5
IO268NB6F25	AB3
IO268PB6F25	AC3
IO269NB6F25	AC2
IO269PB6F25	AD2
IO270NB6F25	Y7
IO270PB6F25	AA7
IO271NB6F25	AA4
IO271PB6F25	AB4
IO272NB6F25	Y6
IO272PB6F25	AA6
IO273NB6F25	AB1*
IO273PB6F25	AE2*
IO274NB6F25	W8
IO274PB6F25	Y8
IO275NB6F25	Y5
IO275PB6F25	AA5
IO277NB6F25	AA2
IO277PB6F25	AA1
IO278NB6F26	W6
IO278PB6F26	W7
IO279NB6F26	Y3
IO279PB6F26	Y4
IO280NB6F26	V8
IO280PB6F26	V9
IO281NB6F26	Y1

FG896	
AX2000 Function	Pin Number
IO281PB6F26	Y2
IO282NB6F26	V5
IO282PB6F26	W5
IO284NB6F26	V7
IO284PB6F26	V6
IO285NB6F26	W3
IO285PB6F26	W4
IO286NB6F26	U8
IO286PB6F26	U9
IO287NB6F26	W1
IO287PB6F26	W2
IO288NB6F26	U7
IO288PB6F26	U6
IO290NB6F27	U4
IO290PB6F27	V4
IO291NB6F27	U3
IO291PB6F27	V3
IO292NB6F27	T5
IO292PB6F27	U5
IO293NB6F27	U2
IO293PB6F27	V2
IO294NB6F27	T8
IO294PB6F27	T9
IO296NB6F27	T1
IO296PB6F27	U1
IO298NB6F27	T7
IO298PB6F27	T6
IO299NB6F27	R2
IO299PB6F27	T2
Bank 7	
IO300NB7F28	R8
IO300PB7F28	R9
IO302NB7F28	R4
IO302PB7F28	R5
IO303NB7F28	P1

CG624	
AX1000 Function	**Pin Number**
IO63PB1F5	G18
Bank 2	
IO64NB2F6	M17
IO64PB2F6	G22
IO65NB2F6	J21
IO65PB2F6	J20
IO66NB2F6	L23
IO66PB2F6	K20
IO67NB2F6	F23
IO67PB2F6	E23
IO68NB2F6	L18
IO68PB2F6	K18
IO70NB2F6	E24
IO70PB2F6	D24
IO71NB2F6	H23
IO71PB2F6	G23
IO72NB2F6	L19
IO72PB2F6	K19
IO74NB2F7	J22
IO74PB2F7	H22
IO75NB2F7	N23
IO75PB2F7	M23
IO76NB2F7	N17
IO76PB2F7	N16
IO77NB2F7	L22
IO77PB2F7	K22
IO78NB2F7	M19
IO78PB2F7	M18
IO79NB2F7	N19
IO79PB2F7	N18
IO80NB2F7	L21
IO80PB2F7	L20
IO82NB2F7	P18
IO82PB2F7	P17
IO83NB2F7	N22
IO83PB2F7	M22

CG624	
AX1000 Function	**Pin Number**
IO84NB2F7	M20
IO84PB2F7	M21
IO86NB2F8	E25
IO86PB2F8	D25
IO87NB2F8	L24
IO87PB2F8	K24
IO88NB2F8	G24
IO88PB2F8	F24
IO89NB2F8	J25
IO90NB2F8	G25
IO90PB2F8	F25
IO91NB2F8	L25
IO91PB2F8	K25
IO92NB2F8	J24
IO92PB2F8	H24
IO93PB2F8	J23
IO94NB2F8	N24
IO94PB2F8	M24
IO95NB2F8	N25
IO95PB2F8	M25
Bank 3	
IO96NB3F9	T18
IO96PB3F9	R18
IO97NB3F9	N20
IO97PB3F9	P24
IO98NB3F9	P20
IO98PB3F9	P19
IO99NB3F9	P21
IO100NB3F9	T22
IO100PB3F9	W24
IO101NB3F9	R22
IO101PB3F9	P22
IO102NB3F9	U19
IO102PB3F9	T19
IO104NB3F9	V20
IO104PB3F9	U20

CG624	
AX1000 Function	**Pin Number**
IO105NB3F9	R23
IO105PB3F9	P23
IO106NB3F9	R19
IO106PB3F9	R20
IO107NB3F10	AB24
IO108NB3F10	R25
IO108PB3F10	P25
IO109NB3F10	U25
IO109PB3F10	T25
IO110NB3F10	U24
IO110PB3F10	U23
IO112NB3F10	T24
IO112PB3F10	R24
IO113NB3F10	Y25
IO113PB3F10	W25
IO114NB3F10	V23
IO114PB3F10	V24
IO116NB3F10	AA24
IO116PB3F10	Y24
IO117NB3F10	AB25
IO117PB3F10	AA25
IO118NB3F11	T20
IO118PB3F11	R21
IO120NB3F11	W22
IO120PB3F11	W23
IO122NB3F11	V22
IO122PB3F11	U22
IO124NB3F11	Y23
IO124PB3F11	AA23
IO126NB3F11	V21
IO126PB3F11	U21
IO128NB3F11	Y22
IO128PB3F11	Y21
Bank 4	
IO129NB4F12	W20
IO129PB4F12	Y20